

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS:

1. - 73. (Canceled)

74. (Currently Amended) An RFID tag, comprising:

a first substrate having oppositely facing first and second surfaces;

a second substrate having oppositely facing first and second surfaces, the first surface of the second substrate facing the second surface of the first substrate;

an RFID integrated circuit fixed to the first substrate so that the RFID integrated circuit and the first substrate together form an RFID integrated circuit module;

an RFID antenna disposed on the first surface of the second substrate and electrically coupled to the RFID integrated circuit via a non-contact coupling;

an electrically conductive region disposed on the second surface of the second substrate and electrically coupled to the RFID integrated circuit via a non-contact coupling;

an a first adhesive layer between a surface of the RFID integrated circuit facing the second substrate and the first surface of the second substrate, the first adhesive layer attaching the RFID integrated circuit module to the second substrate;

the RFID integrated circuit being fixed to the second surface of the first substrate by a second adhesive layer;

at least one electrical coupling circuit on the second surface of the first substrate and connected to the RFID integrated circuit, the at least one electrical coupling circuit electrically coupling the RFID integrated circuit to the electrically conductive region via a non-contact coupling, and the at least one electrical coupling circuit electrically coupling the RFID integrated circuit to the RFID antenna via a non-contact coupling;

an adhesion modifying layer associated with the first and/or second adhesive layer, the adhesion modifying layer modifying adhesion of the RFID integrated circuit or the at least one electrical coupling circuit so that the RFID integrated circuit and/or the at least one electrical coupling circuit is modified if the RFID integrated circuit module is removed from the second substrate to indicate tampering of the RFID tag;
and

an attachment layer on the second surface of the second substrate for attaching the second substrate to a receiving surface.

75. (Currently Amended) An RFID tag, comprising:
a first substrate having oppositely facing first and second surfaces;
a second substrate having oppositely facing first and second surfaces, the first surface of the second substrate facing the second surface of the first substrate;
an RFID integrated circuit fixed to the first substrate so that the RFID integrated circuit and the first substrate together form an RFID integrated circuit module;
an RFID antenna disposed on the second surface of the second substrate and electrically coupled to the RFID integrated circuit via a non-contact coupling;

an a first adhesive layer between a surface of the RFID integrated circuit facing the second substrate and the first surface of the second substrate, the first adhesive layer attaching the RFID integrated circuit module to the second substrate; the RFID integrated circuit being fixed to the second surface of the first substrate by a second adhesive layer;

at least one electrical coupling circuit on the second surface of the first substrate and connected to the RFID integrated circuit, the at least one electrical coupling circuit electrically coupling the RFID integrated circuit to the electrically conductive region via a non-contact coupling, and the at least one electrical coupling circuit electrically coupling the RFID integrated circuit to the RFID antenna via a non- contact coupling;

an adhesion modifying layer associated with the first and/or second adhesive layer, the adhesion modifying layer modifying adhesion of the RFID integrated circuit or the at least one electrical coupling circuit so that the RFID integrated circuit and/or the at least one electrical coupling circuit is modified if the RFID integrated circuit module is removed from the second substrate to indicate tampering of the RFID tag;
and

an attachment layer on the second surface of the second substrate for attaching the second substrate to a receiving surface.

76. (Previously Presented) The RFID tag of claim 74, further including an attachment modifying layer modifying the attachment of the electrically conductive region such that the electrically conductive region is disrupted if the second substrate is tampered or removed from the receiving surface.

77. (Previously Presented) The RFID tag of claim 76, wherein the RFID integrated circuit is adapted to detect at least one electrical property of the electrically conductive region so that modifying the at least one electrical property of the electrically conductive region is detected by the RFID integrated circuit.

78. (Canceled)

79. (Canceled)

80. (Canceled)

81. (Previously Presented) The RFID tag of claim 74, wherein the attachment layer is arranged between the electrically conductive region and the receiving surface.

82. (Previously Presented) The RFID tag of claim 76, wherein the attachment modifying layer is arranged between the second surface of the second substrate and the electrically conductive region.

83. (Previously Presented) The RFID tag of claim 76, wherein the attachment layer is a layer of adhesive and the attachment modifying layer is an adhesion modifying layer.

84. (Previously Presented) The RFID tag of claim 77, wherein the RFID integrated circuit is adapted to record or transmit information representing the at least one electrical property of the electrically conductive region.

85. (Previously Presented) The RFID tag of claim 74, further comprising a power source within the tag and coupled to the RFID integrated circuit.

86. (Previously Presented) The RFID tag of claim 77, wherein the at least one electrical property is an electrical impedance value of the electrically conductive region.

87. (Canceled)

88. (Previously Presented) The RFID tag of claim 74, wherein the non-contact coupling is a capacitive coupling or an inductive coupling.

89. (Canceled)

90. (Currently Amended) The RFID tag of claim 75, further including an attachment modifying layer modifying the attachment of the RFID antenna ~~electrically conductive region~~ such that the ~~electrically conductive region~~ RFID antenna is disrupted if the second substrate is tampered or removed from the receiving surface.

91. (Currently Amended) The RFID tag of claim ~~90~~ 75, wherein the attachment layer is a layer of adhesive and the attachment modifying layer is an adhesion modifying layer.

92. (Previously Presented) The RFID tag of claim 75, further comprising a power source within the tag and coupled to the RFID integrated circuit.

93. (Canceled)

94. (Previously Presented) The RFID tag of claim 75, wherein the non-contact coupling is a capacitive coupling or an inductive coupling.

95. (Canceled)

96. (Currently Amended) The RFID tag of claim ~~79~~ 77, further comprising a power source within the tag and coupled to the RFID integrated circuit.

97. (Canceled)

98. (Currently Amended) The RFID tag of claim ~~79~~ 77, wherein the non-contact coupling is a capacitive coupling or an inductive coupling.

99. (Canceled)

100. (Currently Amended) The RFID tag of claim 74, wherein a surface area of the second surface of the first substrate is smaller than a surface area of the first surface of the second substrate.

101. (Currently Amended) The RFID tag of claim 75, wherein a surface area of the second surface of the first substrate is smaller than a surface area of the first surface of the second substrate.

102. (Canceled)

103. (Canceled)

104. (Currently Amended) A method of manufacturing an RFID tag, comprising:

forming an RFID integrated circuit module by fixing an RFID integrated circuit to a first substrate having oppositely facing first and second surfaces, the RFID integrated circuit being fixed to the second surface of the first substrate by a first adhesive layer;

forming an RFID antenna on ~~the first surface of~~ a second substrate having oppositely facing first and second surfaces, the RFID antenna being formed on the first surface of the second substrate, the first surface of the second substrate facing the second surface of the first substrate;

forming an electrically conductive region on the second surface of the second substrate;

forming at least one electrical coupling circuit on the second surface of the first substrate and connected to the RFID integrated circuit, the at least one electrical coupling circuit electrically coupling the RFID integrated circuit to the electrically conductive region via a non-contact coupling, and the at least one electrical coupling circuit electrically coupling the RFID integrated circuit to the RFID antenna via a non-contact coupling;

forming an adhesion modifying layer associated with the RFID integrated circuit and/or the at least one electrical coupling circuit;

forming a second adhesive layer on the second surface of the first substrate over the RFID integrated circuit and the at least one electrical coupling circuit; and

attaching the RFID integrated circuit module to the second substrate via ~~[[an]]~~ the second adhesive layer by applying the second surface of the first substrate to the first surface of the second substrate ~~between a surface of the RFID integrated circuit facing the second substrate and the first surface of the second substrate~~ so that the RFID antenna is electrically coupled to the RFID integrated circuit via a non-contact coupling and the electrically conductive region is electrically coupled to the RFID integrated circuit via a non-contact coupling; and

the adhesion modifying layer modifying adhesion of the RFID integrated circuit and/or the at least one electrical coupling circuit so that the RFID integrated circuit and/or the at least one electrical coupling circuit is modified if the RFID integrated circuit module is removed from the second substrate to indicate tampering of the RFID tag.

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105. (Currently Amended) A method of manufacturing an RFID tag,
comprising:

forming an RFID integrated circuit module by fixing an RFID integrated circuit
via a first adhesive layer to a first substrate having oppositely facing first and second
surfaces;

forming an RFID antenna on a surface of a second substrate, the second
substrate facing the second surface of the first substrate;

forming at least one electrical coupling circuit on the second surface of the
first substrate and connected to the RFID integrated circuit, the at least one electrical
coupling circuit electrically coupling the RFID integrated circuit to the RFID antenna
via a non-contact coupling;

forming an adhesion modifying layer associated with the RFID integrated
circuit and/or the at least one electrical coupling circuit;

forming a second adhesive layer on the second surface of the first substrate
over the RFID integrated circuit and the at least one electrical coupling circuit;

and

attaching the RFID integrated circuit module to the second substrate via ~~[[an]]~~
the second adhesive layer by applying the second surface of the first substrate to the
second substrate ~~between a surface of the RFID integrated circuit facing the second~~
~~substrate and the second substrate~~ so that the RFID antenna is electrically coupled
to the RFID integrated circuit via a non-contact coupling; and

the adhesion modifying layer modifying adhesion of the RFID integrated
circuit and/or the at least one electrical coupling circuit so that the RFID integrated
circuit or the at least one electrical coupling circuit is modified if the RFID integrated

circuit module is removed from the second substrate to indicate tampering of the
RFID tag.

106. (Currently Amended) The method of claim 105, wherein the second substrate has a first surface facing the first substrate and a second surface opposite the first surface, and the RFID antenna is formed on the second surface of ~~[[a]]~~ the second substrate.